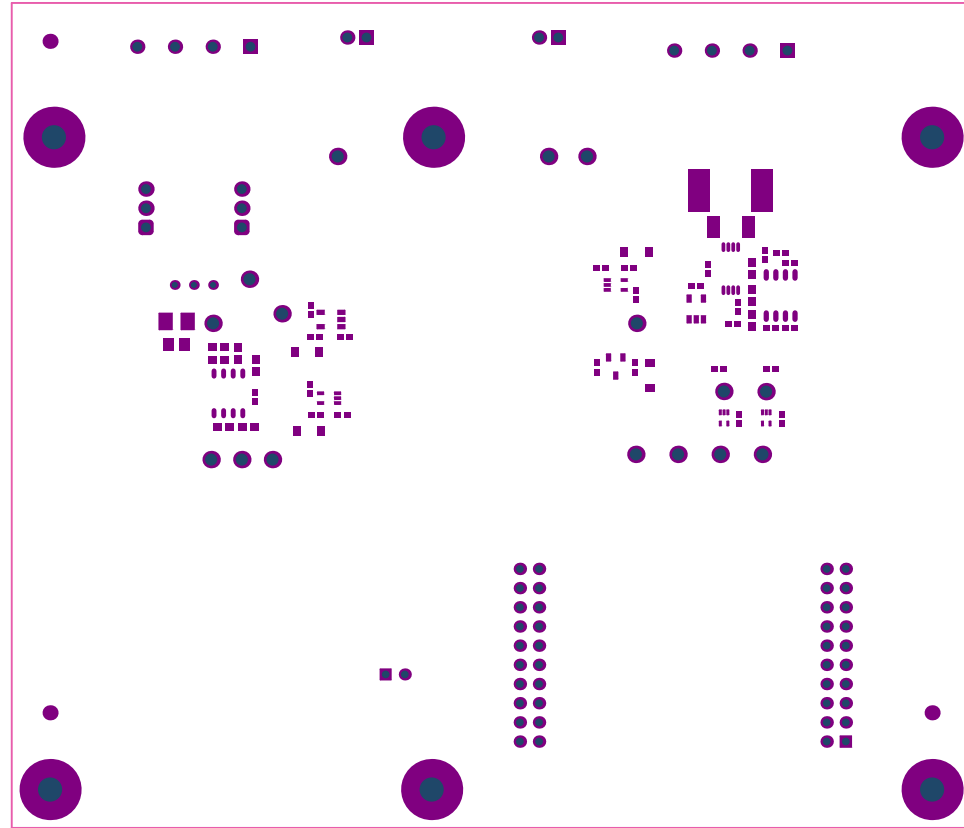
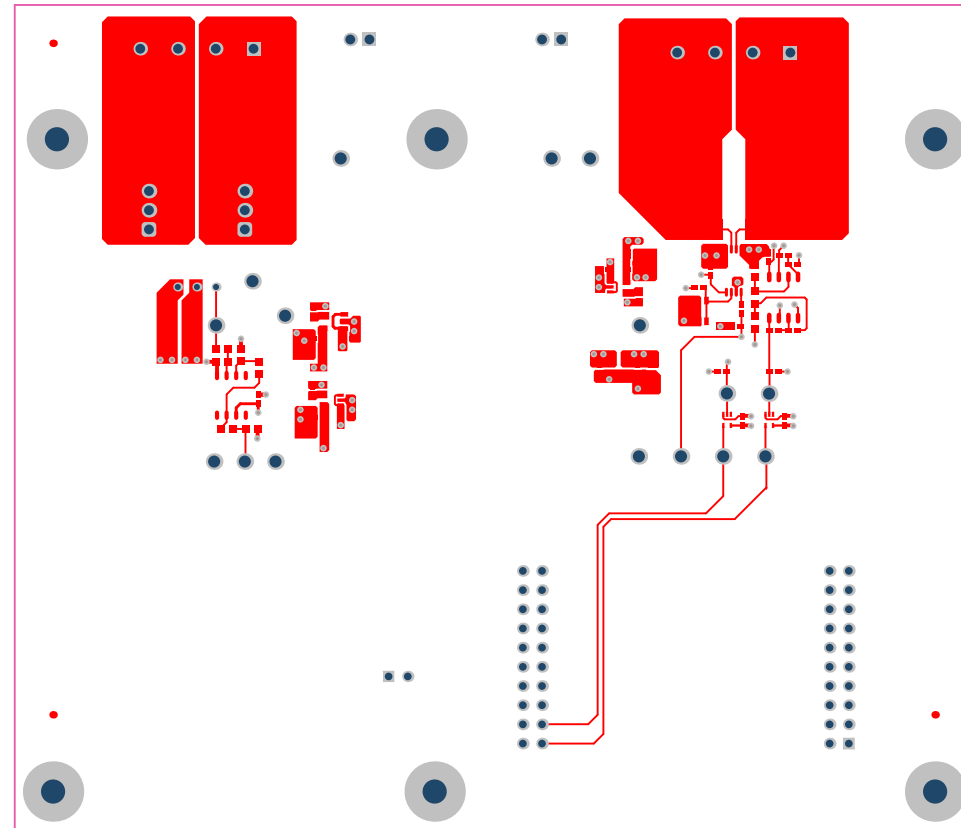


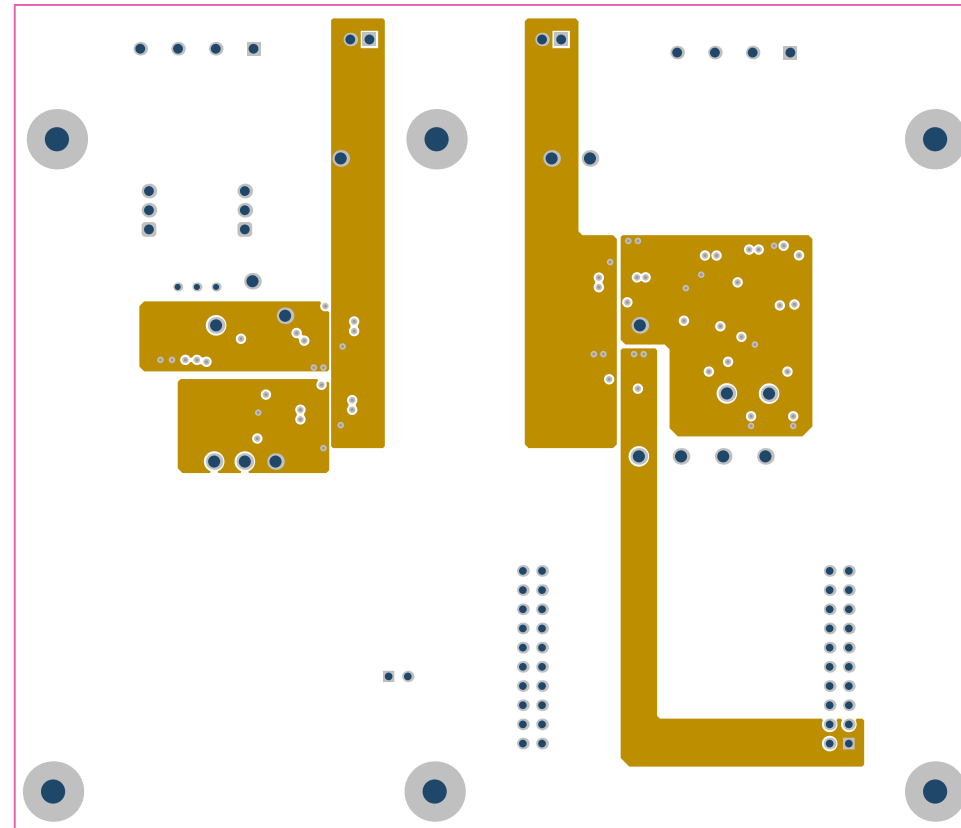
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01598		
PLOT NAME = Top Overlay	GENERATED : 7/10/2018 9:22:54 AM		TEXAS INSTRUMENTS



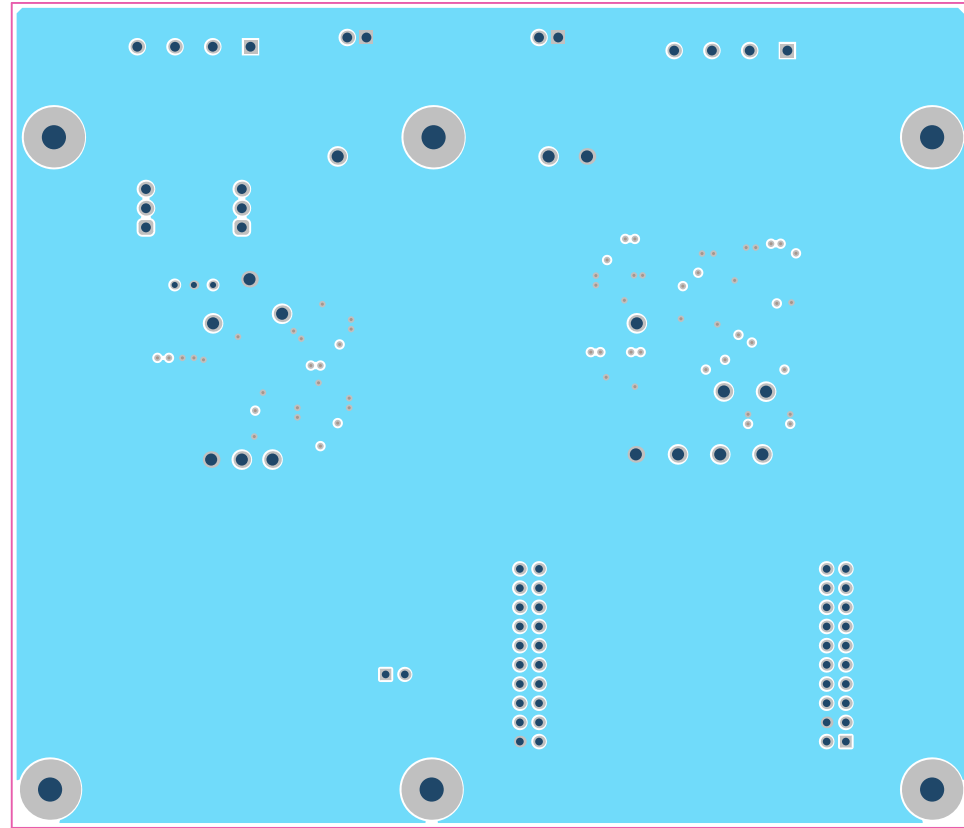
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01598		
PLOT NAME = Top Solder Mask	GENERATED : 7/10/2018 9:22:56 AM	TEXAS INSTRUMENTS	



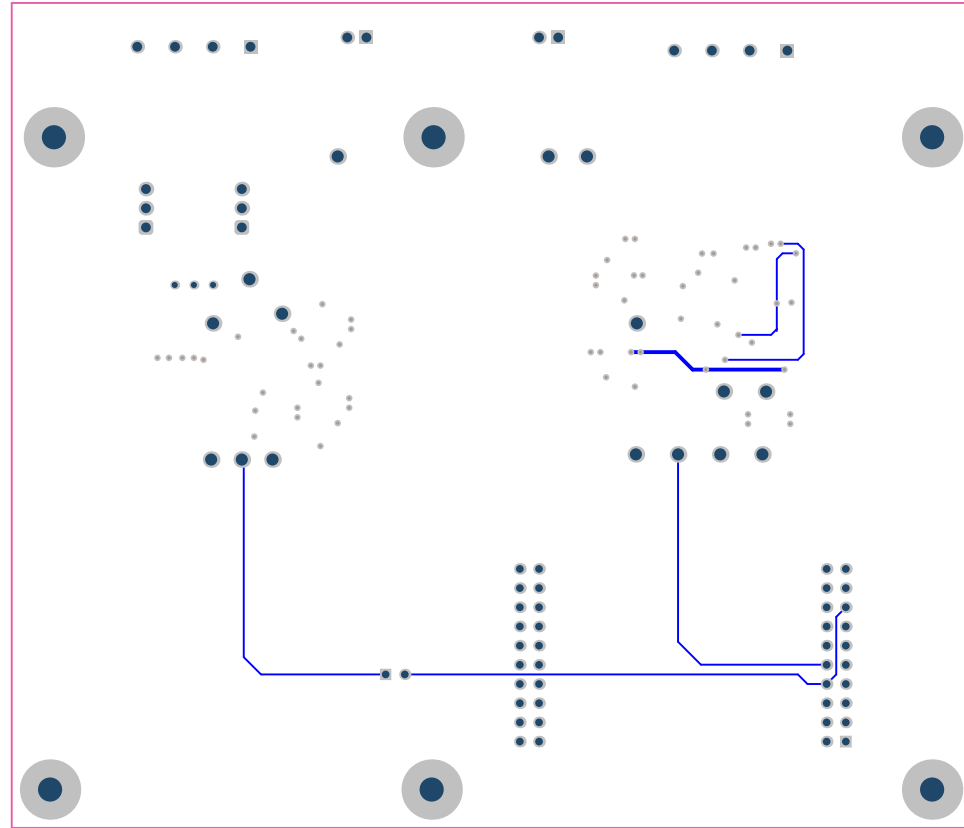
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01598		
PLOT NAME = Top Layer	GENERATED : 7/10/2018	9:22:58 AM	TEXAS INSTRUMENTS



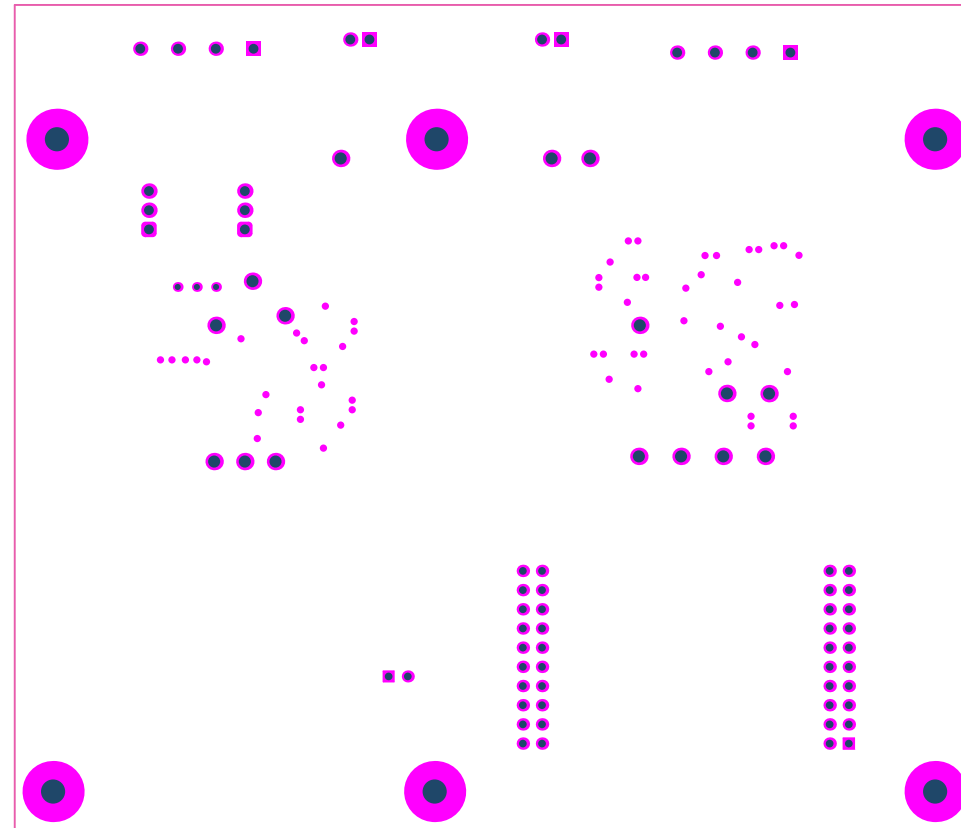
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: 01598		
PLOT NAME = Signal Layer 1	GENERATED : 7/10/2018 9:23:00 AM		TEXAS INSTRUMENTS



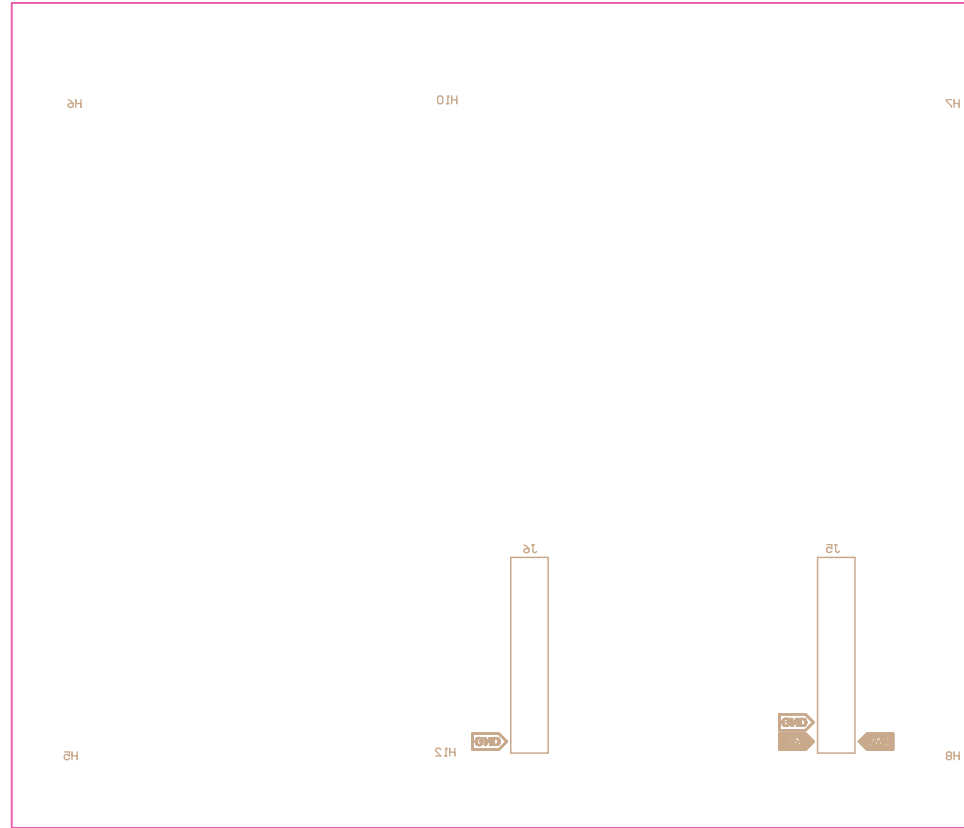
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: 01598		
PLOT NAME = Signal Layer 2	GENERATED : 7/10/2018 9:23:02 AM	TEXAS INSTRUMENTS	



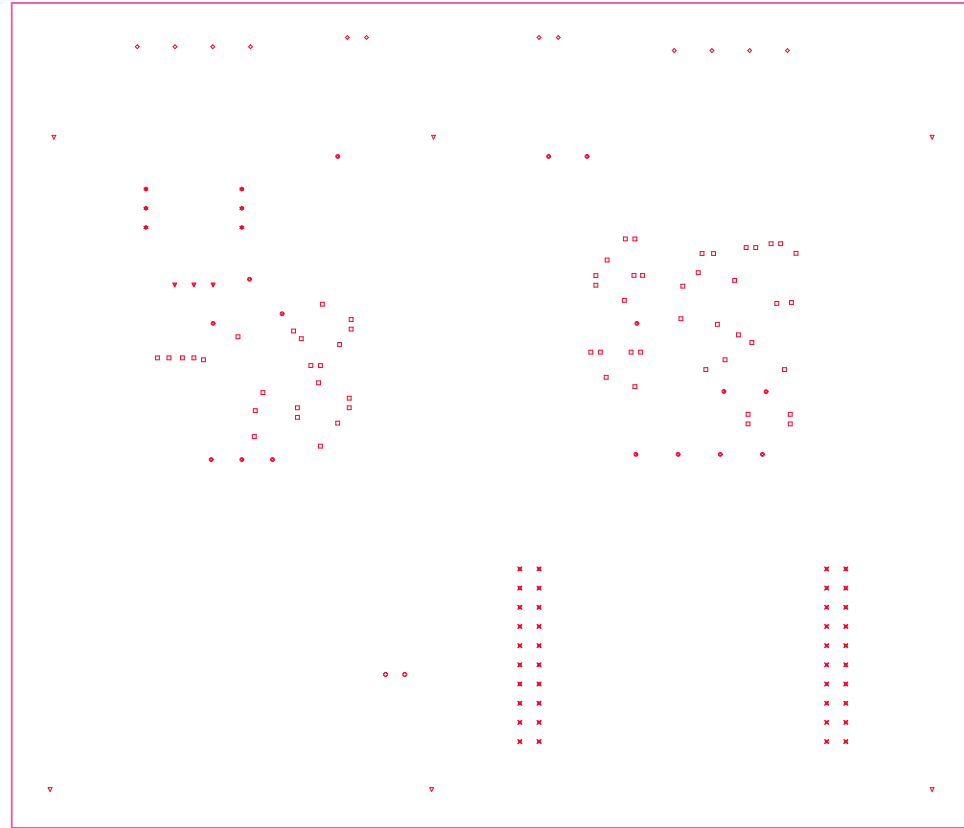
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01598		
PLOT NAME = Bottom Layer	GENERATED : 7/10/2018	9:23:04 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01598		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/10/2018 9:23:05 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01598		
PLOT NAME = Bottom Overlay	GENERATED : 7/10/2018	9:23:06 AM	TEXAS INSTRUMENTS

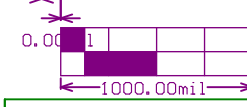


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
□	61	16,00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
▽	3	31,50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	+/-7.87mil
⊗	2	40,00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	40	40,16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	51,18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	+/-7.87mil
◇	12	51,18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	16	63,00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
▽	6	125,98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	146 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01598		
PLOT NAME = Drill Drawing	GENERATED : 7/10/2018	9:23:07 AM	TEXAS INSTRUMENTS



0.00mil



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01598	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01598		
PLOT NAME = Board Dimensions	GENERATED : 7/10/2018 9:23:09 AM	TEXAS INSTRUMENTS	

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